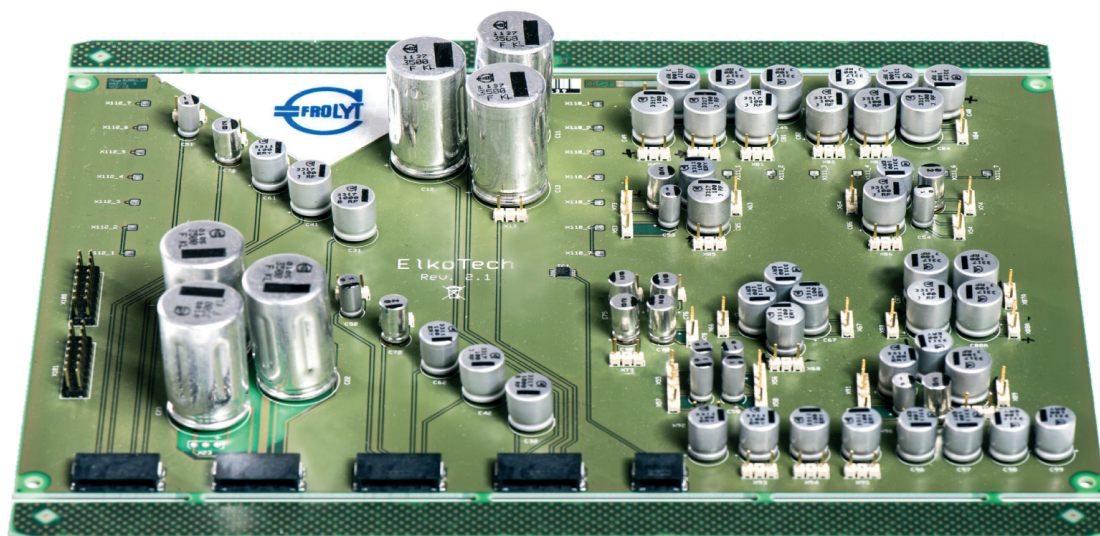


Radial Electrolytic Capacitors of FROLYT developed for „PIN-IN-PASTE“

In a joint project with IMM Elektronik GmbH, Mittweida, TU Dresden, Institute for packaging of integrated circuits and FROLYT Freiberg test board examinations were performed with the developed Electrolytic Capacitors and the “PIN-IN-PASTE” process. Thereby the technology development, analytics and the reclamation of statements of reliability were set.



Heterogeneously printed circuit boards, both SMD and THT components contain, pass through processes of soldering (reflow soldering and wave soldering). In order to save costs the “Pin-IN-PASTE technology is one of the most efficient solutions. In addition to the SMD components the draw lead component parts were assembled and soldered in a optimized reflow process. Standard electrolytic capacitors which processing in wave soldering are inappropriate for reflow soldering.

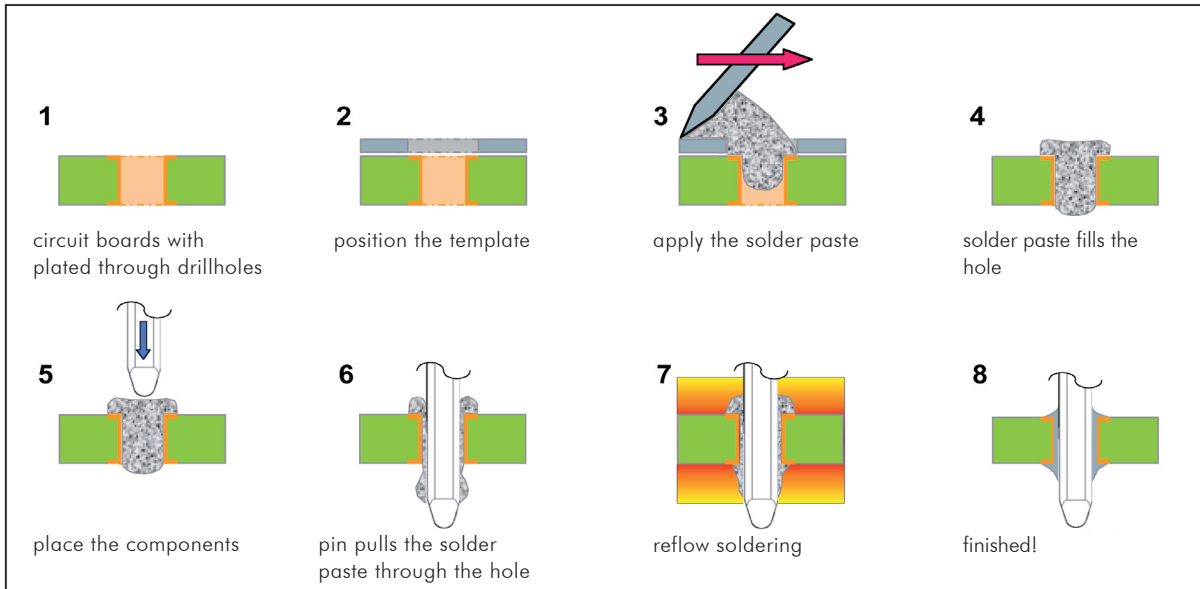
FROLYT developed electrolytic capacitors with special heat resistance, which also support the application of heat into the throughplatings of the circuit boards during the reflow soldering process.

The special capacitors are available in the dimensions $\varnothing 5,5 \times 12,0$ mm up to $\varnothing 18,0 \times 36,5$ mm.



Through-Hole-Technology

The steps of the "Pin-In-Paste" process



source image: Phoenix Contact GmbH & Co. KG